OKMETIC

Okmetic Company Presentation

Atte Haapalinna June 18th, 2009

Okmetic in brief

Okmetic supplies tailor-made silicon wafers for sensor and semiconductor industries. In addition, we sell our technological expertise.

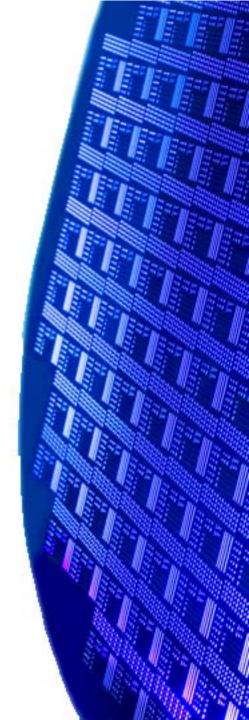
Our silicon wafers are part of a further processing chain that produces end products that improve human interaction and the quality of life.

Okmetic is the world's leading supplier of sensor wafers and an esteemed technological partner.

Net sales (2008): 67.9 million euro

Operating profit: 12.5 % of net sales

Number of personnel (2008 average): 364



Production



Vantaa plant, Finland

- Crystal growth
- Sensor wafers
- Demanding semiconductor wafers
- Advanced wafers (SOI)

Allen plant, Texas, USA

Value adding wafers (EPI)

Contract manufacturing, Japan and China

Semiconductor wafers



Okmetic products

- Silicon-based solutions for sensor and semiconductor applications
- Single-side polished (SSP), double-side polished (DSP), silicon-on-insulator (SOI), epitaxial and CAP wafers
 - Diameter: 100...200 mm
 - Growth method: Cz, MCz
 - Crystal orientation: <100>, <111>, <110>
 - Types and dopants:
 - N antimony, arsenic, phosphorus, red phosphorus
 - P boron
 - Resistivity: 0.0015...1500 ohm-cm







Okmetic High Resistivity MCz wafers

- Diameter: Primarily 150mm, other diameters upon request
- Growth method: Dedicated MCz pullers, tailored growth processes and production materials
- Crystal orientation: <100>, <111>, <110>
- Types and Resistivities:
 - N type specifications typically at some 500 Ohm-cm.
 >1000 Ohm-cm material has been delivered in quantity
 - P type specification of 1000 Ohm-cm is typical, even higher limits have been tested
- Alternative PiN-diode products based on high resistivity (1 kOhm) epilayers



Okmetic High Resistivity MCz wafers

- Interstitial oxygen of the MCz improves the radiation hardness of silicon
- At the same time, oxygen gives rise to thermal donors
- Effects of these donors are suppressed with the use of
 - Optimized low-oxygen material
 - Wafering process tailoring
 - Device process optimization
- Radiation hardness achieved with MCz has been extensively studied
 - For example:
 - E. Tuovinen, et al, Czochralski silicon detectors irradiated with 24 GeV/c and 10 MeV protons, Phys. Res. A 568 (2006) 83-88.
 - J. Härkönen et al, MagneticCzochralski silicon as detector material, Phys.Res. A579 (2007) 648-652.

